30V N-Channel Trench Power MOSFET

General Description

The SJS3404 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

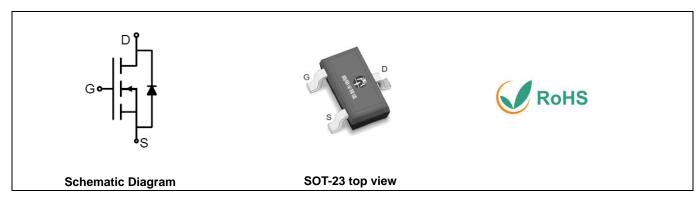
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	30	V
R _{DS(ON)_TYP}	15.1	mΩ
I _D	7	А
Q _G	19	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJS3404	3404	SOT-23	Tape	\	/	3000 Pcs

Table 1. Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _D S	Drain-Source Voltage (V _{GS} =0V)	30	V
V _G s	Gate-Source Voltage (V _{DS} =0V)	±20	V
1-	Drain Current-Continuous(T _A =25°C)	7	А
I _D	Drain Current-Continuous(T _A =100°C)	4.4	Α
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	28	А
P _D	Maximum Power Dissipation(T _A =25°C)	1.5	W
PD	Maximum Power Dissipation(T _A =100°C)	0.6	W
Eas	Avalanche energy (Note 2)	30	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{ hetaJA}$	Thermal Resistance, Junction-to-Ambient		83	°C/W



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Table 3. Electrical Characteristics ($T_J=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	•					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	30			V
	7 0 1 1/1 1 2 1 0 1	V _{DS} =30V, V _{GS} =0V T _J =25°C			1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =125°C			100	μΑ
Igss	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1		2.5	V
G FS	Forward Transconductance	V _{DS} =5V, I _D =3A		6.7		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =3A T _J =25°C		15.1	19.6	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =2A T _J =25°C		21.3	28.3	mΩ
Dynamic Chara	octeristics			1		
Ciss	Input Capacitance			584		pF
Coss	Output Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		74		pF
Crss	Reverse Transfer Capacitance			58		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.46		Ω
Switching Para	meters		•	•	•	•
t _{d(on)}	Turn-on Delay Time			4		nS
t _r	Turn-on Rise Time	V _{GS} =10V, V _{DS} =15V,		11		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time	$R_L=5Ω$, $R_{GEN}=3Ω$		24		nS
t _f	Turn-Off Fall Time			2		nS
Qg	Total Gate Charge			19		nC
Q _{gs}	Gate-Source Charge	V _{GS} =10V, V _{DS} =15V, I _D =3A		2		nC
Q_{gd}	Gate-Drain Charge			2		nC
Source-Drain D	liode Characteristics		•		•	
I _{SD}	Source-Drain Current (Body Diode)				7	А
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =3A			1.2	V
t _{rr}	Reverse Recovery Time	I=3A, dI/dt=100A/μs		8.5		ns
Qrr	Reverse Recovery Charge	I _F =3A, dI/dt=100A/μs		3.3		nC

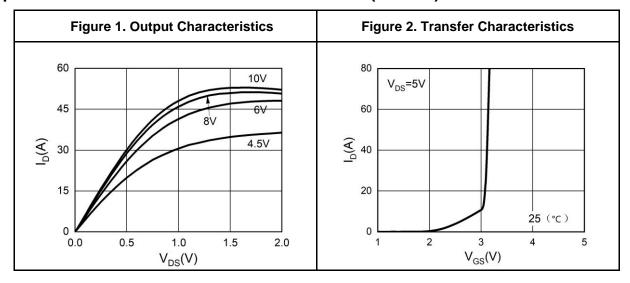
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

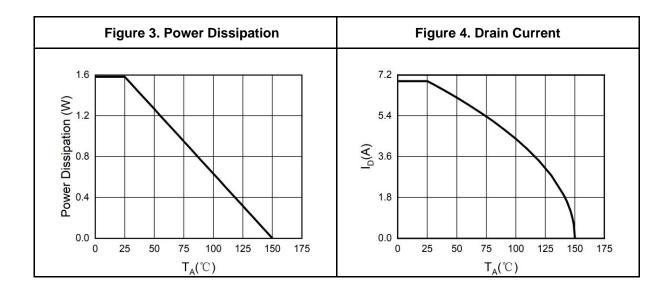
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=30V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

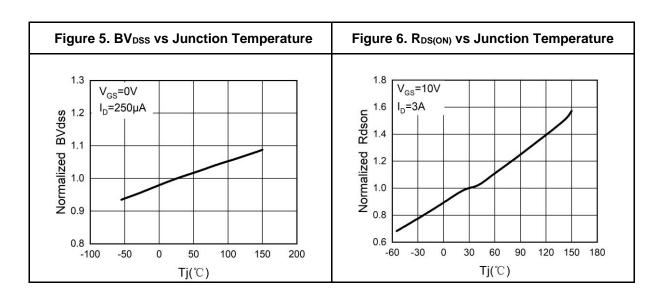
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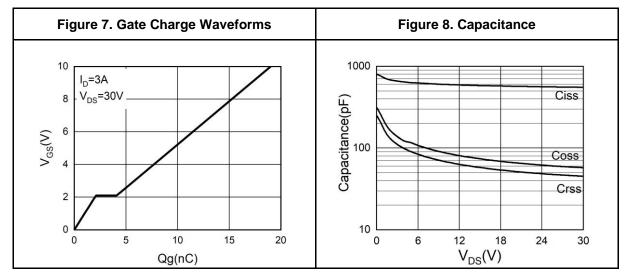
Typical Electrical And Thermal Characteristics (Curves)

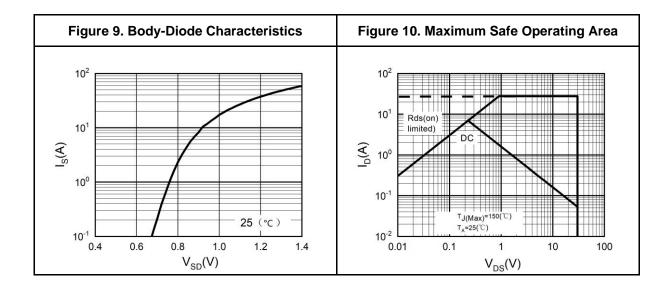






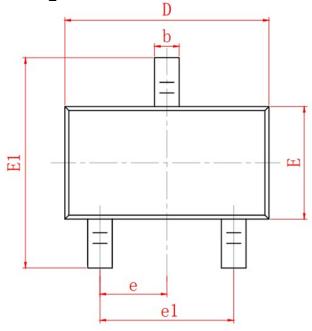
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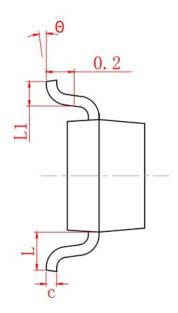


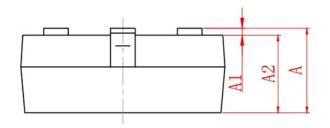




SOT-23 Package Information







SYMBOL	MIN	NOM	MAX		
А	0.90	1.05	1.20		
A1	0.00	0.05	0.10		
A2	0.90	1.00	1.10		
b	0.30	0.40	0.50		
С	0.08	0.10	0.15		
D	2.80	2.90	3.00		
Е	1.20	1.30	1.40		
E1	2.30	2.40	2.50		
L	0.30	0.40	0.50		
θ	0°	5°	10°		
L1	0.55 REF				
е	0.95 BSC				
e1	1.90 REF				



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Attention

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